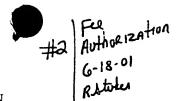


Docket No.: 50090-270



## UTILITY PATENT APPLICATION UNDER 37 CFR 1.53(b)

Box PATENT APPLICATION Commissioner for Patents Washington, DC 20231 Sir:

Transmitted herewith for filing is the patent application of:

INVENTOR: Katsunobu HORI, Nobuo FUJIWARA, Takashi WATADANI, Makoto

**NAGANO** 

FOR: SEMICONDUCTOR DEVICE HAVING A LAYERED WIRING STRUCTURE

Enclose	ed are:						
$\boxtimes$	28 pages of specification, claims, abstract.						
$\boxtimes$	Declaration and Power of Attorney.						
$\overline{\boxtimes}$	Priority Claimed.						
$\overline{\boxtimes}$	Certified copy of Japanese Patent Application No. 2000-160254						
	9 sheets of formal drawing.						
$\boxtimes$	An assignment of the invention to Mitsubishi Denki Kabushiki Kaisha						
	and the assignment recordation fee.						
	An associate power of attorney.						
$\Box$	A verified statement to establish small entity status under 37 CFR 1.9 and 37 CFR 1.27.						
$\overline{\boxtimes}$	Information Disclosure Statement, Form PTO-1449 and reference.						
$\boxtimes$	Return Receipt Postcard						
	•						

The filing fee has been calculated as shown below:

	NO. OF CLAIMS		EXTRA CLAIMS	RATE	AMOUNT
Total Claims	16	-20	0	\$18.00	\$0.00
Independent Claims	3	-3	0	\$80.00	\$0.00
•	\$0.00				
	\$710.00				
Total of Above Calculations					\$710.00
	\$0.00				
	\$40.00				
The second sections	\$750.00				



PATENT TRADEMARK OFFICE

- Please charge my Deposit Account No. 500417 in the amount of \$750.00. A duplicate copy of this sheet is enclosed.
- The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 500417. A duplicate copy is enclosed.
  - Any additional filing fees required under 37 CFR 1.16.
- The Commissioner is hereby authorized to charge payment of the following fees during the pendency of this application or credit any overpayment to Deposit Account No. 500417. A duplicate copy of this sheet is enclosed.
  - Any patent application processing fees under 37 CFR 1.17.
  - Any filing fees under 37 CFR 1.16 for presentation of extra claims.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Stephen A. Becker Registration No. 26,527

600 13<sup>th</sup> Street, N.W. Washington, DC 20005-3096 (202) 756-8000 SAB:klm **Date: January 10, 2001** 

Facsimile: (202) 756-8087

Docket No.: 50090-270

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Katsunobu HORI, et al.

Serial No.:

Group Art Unit:

Filed: January 10, 2001

Examiner:

For: SEMICONDUCTOR DEVICE HAVING A LAYERED WIRING STRUCTURE



Commissioner for Patents Washington, DC 20231

Sir:

In accordance with the provisions of 35 U.S.C. 119, Applicants hereby claim the priority of:

Japanese Patent Application No. 2000-160254, filed May 30, 2000

cited in the Declaration of the present application. A certified copy is submitted herewith.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Stephen A. Becker

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600 13<sup>th</sup> Street, N.W. Washington, DC 20005-3096 (202) 756-8000 SAB:klm

**Date: January 10, 2001** Facsimile: (202) 756-8087